

What is claimed is:

1. A packaged photosensitive element,
comprising:
a photosensitive element, having electrical
connections; and
a clear plastic package, having said
photosensitive element mounted therein, and providing
a perimeter connected to said electrical connections
on said photosensitive element, said clear plastic
package being clear at all locations within said
perimeter.

2. An element as in claim 1, wherein said
photosensitive element is a CMOS active pixel sensor.

3. An element as in claim 1, wherein said
plastic package is acrylic.

4. A method of packaging an image sensor,
comprising:
obtaining an image sensor with electrical connections;

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connecting said electrical connections of said image
5 sensor to corresponding connections on a perimeter of said
image sensor; and

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